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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, FlexIO, SPI, UART/USART, USB
Peripherals	DMA, I²S, PWM, WDT
Number of I/O	30
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 14x16b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	36-XFBGA
Supplier Device Package	36-XFBGA (3.5x3.5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mkl27z64vda4r

Email: info@E-XFL.COM Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Voltage range: 1.71 to 3.6 V
- Flash write voltage range: 1.71 to 3.6 V
- Temperature range: –40 to 105 °C

Packages
- 64 LQFP 10mm x 10mm, 0.5mm pitch, 1.6mm thickness
- 36 XFBGA 3.5mm x 3.5mm, 0.5mm pitch, 0.5mm thickness
- 32 QFN 5mm x 5mm, 0.5mm pitch, 0.65mm thickness
- 64 MAPBGA 5mm x 5mm, 0.5mm pitch, 1.23mm thickness (Package Your Way)
- 48 QFN 7mm x 7mm, 0.5mm pitch, 0.65mm thickness (Package Your Way)

Security and Integrity
- 80-bit unique identification number per chip
- Advanced flash security
- Hardware CRC module

I/O
- Up to 51 general-purpose input/output pins

Low Power
- Down to 46 μA/MHz in very low power run mode
- Down to 1.68 μA in stop mode (RAM + RTC retained)
- Six flexible static modes

NOTE

The 48 QFN and 64 MAPBGA packages supporting MKLx7ZxxVFT4 and MKLx7ZxxVMP4 part numbers for this product are not yet available. However, these packages are included in Package Your Way program for Kinetis MCUs. Visit Freescale.com/KPYW for more details.

Related Resources

Type	Description	Resource
Selector Guide	The Freescale Solution Advisor is a web-based tool that features interactive application wizards and a dynamic product selector.	Solution Advisor
Product Brief	The Product Brief contains concise overview/summary information to enable quick evaluation of a device for design suitability.	KL2xPB[1]
Reference Manual	The Reference Manual contains a comprehensive description of the structure and function (operation) of a device.	KL27P64M48SF2RM[1]
Data Sheet	The Data Sheet includes electrical characteristics and signal connections.	KL27P64M48SF2[1]
Chip Errata	The chip mask set Errata provides additional or corrective information for a particular device mask set.	xN87M[2]
Package drawing	Package dimensions are provided in package drawings.	XFBGA 36-pin: 98ASA00708D LQFP 64-pin: 98ASS23234W QFN 32-pin: 98ASA00615D QFN 48-pin: 98ASA00616D MAPBGA 64-pin: 98ASA00420D

1. To find the associated resource, go to http://www.freescale.com and perform a search using this term.
2. To find the associated resource, go to http://www.freescale.com and perform a search using this term with the "x" replaced by the revision of the device you are using.

The PMC provides Run (Run), and Very Low Power Run (VLPR) configurations in ARM's Run operation mode. In these modes, the MCU core is active and can access all peripherals. The difference between the modes is the maximum clock frequency of the system and therefore the power consumption. The configuration that matches the power versus performance requirements of the application can be selected.

The PMC provides Wait (Wait) and Very Low Power Wait (VLPW) configurations in ARM's Sleep operation mode. In these modes, even though the MCU core is inactive, all of the peripherals can be enabled and operate as programmed. The difference between the modes is the maximum clock frequency of the system and therefore the power consumption.

The PMC provides Stop (Stop), Very Low Power Stop (VLPS), Low Leakage Stop (LLS), and Very Low Leakage Stop (VLLS) configurations in ARM's Deep Sleep operational mode. In these modes, the MCU core and most of the peripherals are disabled. Depending on the requirements of the application, different portions of the analog, logic, and memory can be retained or disabled to conserve power.

The Nested Vectored Interrupt Controller (NVIC), the Asynchronous Wake-up Interrupt Controller (AWIC), and the Low Leakage Wake-Up Controller (LLWU) are used to wake up the MCU from low power states. The NVIC is used to wake up the MCU core from WAIT and VLPW modes. The AWIC is used to wake up the MCU core from STOP and VLPS modes. The LLWU is used to wake up the MCU core from LLS and VLLSx modes.

For additional information regarding operational modes, power management, the NVIC, AWIC, or the LLWU, please refer to the Reference Manual.

The following table provides information about the state of the peripherals in the various operational modes and the modules that can wake MCU from low power modes.

Table 6. Peripherals states in different operational modes

Core mode	Device mode	Descriptions
Run mode	Run	In Run mode, all device modules are operational.
	Very Low Power Run	In VLPR mode, all device modules are operational at a reduced frequency except the Low Voltage Detect (LVD) monitor, which is disabled.
Sleep mode	Wait	In Wait mode, all peripheral modules are operational. The MCU core is placed into Sleep mode.
	Very Low Power Wait	In VLPW mode, all peripheral modules are operational at a reduced frequency except the Low Voltage Detect (LVD) monitor, which is disabled. The MCU core is placed into Sleep mode.

Table continues on the next page...

Table 7. Wakeup source

LLWU pin	Module source or pin name
LLWU_P5	PTB0
LLWU_P6	PTC1
LLWU_P7	PTC3
LLWU_P8	PTC4
LLWU_P9	PTC5
LLWU_P10	PTC6
LLWU_P14	PTD4
LLWU_P15	PTD6
LLWU_M0IF	LPTMR0
LLWU_M1IF	CMP0
LLWU_M2IF	Reserved
LLWU_M3IF	Reserved
LLWU_M4IF	Reserved
LLWU_M5IF	RTC alarm
LLWU_M6IF	Reserved
LLWU_M7IF	RTC seconds

2.1.10 Debug controller

This device supports standard ARM 2-pin SWD debug port. It provides register and memory accessibility from the external debugger interface, basic run/halt control plus 2 breakpoints and 2 watchpoints.

It also supports trace function with the Micro Trace Buffer (MTB), which provides a simple execution trace capability for the Cortex-M0+ processor.

2.1.11 COP

The COP monitors internal system operation and forces a reset in case of failure. It can run from bus clock, LPO, 8/2 MHz internal oscillator or external crystal oscillator. Optional window mode can detect deviations in program flow or system frequency.

The COP has the following features:

- Support multiple clock input, 1 kHz clock(LPO), bus clock, 8/2 MHz internal reference clock, external crystal oscillator
- Can work in Stop/VLPS and Debug mode

2.2.6 CMP

The device contains one high-speed comparator and two 8-input multiplexers for both the inverting and non-inverting inputs of the comparator. Each CMP input channel connects to both muxes.

The CMP includes one 6-bit DAC, which provides a selectable voltage reference for various user application cases. Besides, the CMP also has several module-to-module interconnects in order to facilitate ADC triggering, TPM triggering, and interfaces.

The CMP has the following features:

- Inputs may range from rail to rail
- Programmable hysteresis control
- Selectable interrupt on rising-edge, falling-edge, or both rising or falling edges of the comparator output
- Selectable inversion on comparator output
- Capability to produce a wide range of outputs such as sampled, digitally filtered
- External hysteresis can be used at the same time that the output filter is used for internal functions
- Two software selectable performance levels: shorter propagation delay at the expense of higher power and Low power with longer propagation delay
- DMA transfer support
- Functional in all modes of operation except in VLLS0 mode
- The filter functions are not available in Stop, VLPS, LLS, or VLLSx modes
- Integrated 6-bit DAC with selectable supply reference source and can be power down to conserve power
- Two 8-to-1 channel mux

2.2.7 RTC

The RTC is an always powered-on block that remains active in all low power modes. The time counter within the RTC is clocked by a 32.768 kHz clock sourced from an external crystal using the oscillator or clock directly from RTC_CLKIN pin.

RTC is reset on power-on reset, and a software reset bit in RTC can also initialize all RTC registers.

The RTC module has the following features

- 32-bit seconds counter with roll-over protection and 32-bit alarm

- Full-duplex or single-wire bidirectional mode
- Programmable transmit bit rate
- Double-buffered transmit and receive data register
- Serial clock phase and polarity options
- Slave select output
- Mode fault error flag with CPU interrupt capability
- Control of SPI operation during wait mode
- Selectable MSB-first or LSB-first shifting
- Programmable 8- or 16-bit data transmission length
- Receive data buffer hardware match feature
- 64-bit FIFO mode for high speed/large amounts of data transfers
- Support DMA

2.2.14 I2C

This device contains two I2C modules, which support up to 1 Mbits/s by dual buffer features, and address match to wake MCU from the low power mode.

I2C modules support DMA transfer, and the interrupt condition can trigger DMA request when DMA function is enabled.

The I2C modules have the following features:

- Support for system management bus (SMBus) Specification, version 2
- Software programmable for one of 64 different serial clock frequencies
- Software-selectable acknowledge bit
- Arbitration-lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- START and STOP signal generation and detection
- Repeated START signal generation and detection
- Acknowledge bit generation and detection
- Bus busy detection
- General call recognition
- 10-bit address extension
- Programmable input glitch filter
- Low power mode wakeup on slave address match
- Range slave address support
- DMA support
- Double buffering support to achieve higher baud rate

2.2.17 Port control and GPIO

The Port Control and Interrupt (PORT) module provides support for port control, digital filtering, and external interrupt functions. The GPIO data direction and output data registers control the direction and output data of each pin when the pin is configured for the GPIO function. The GPIO input data register displays the logic value on each pin when the pin is configured for any digital function, provided the corresponding Port Control and Interrupt module for that pin is enabled.

The following figure shows the basic I/O pad structure. This diagram applies to all I/O pins except PTA20/RESET_b and those configured as pseudo open-drain outputs. PTA20/RESET_b is a true open-drain pin without p-channel output driver or diode to the ESD bus. Pseudo open-drain pins have the p-channel output driver disabled when configured for open-drain operation. None of the I/O pins, including open-drain and pseudo open-drain pins, are allowed to go above VDD.

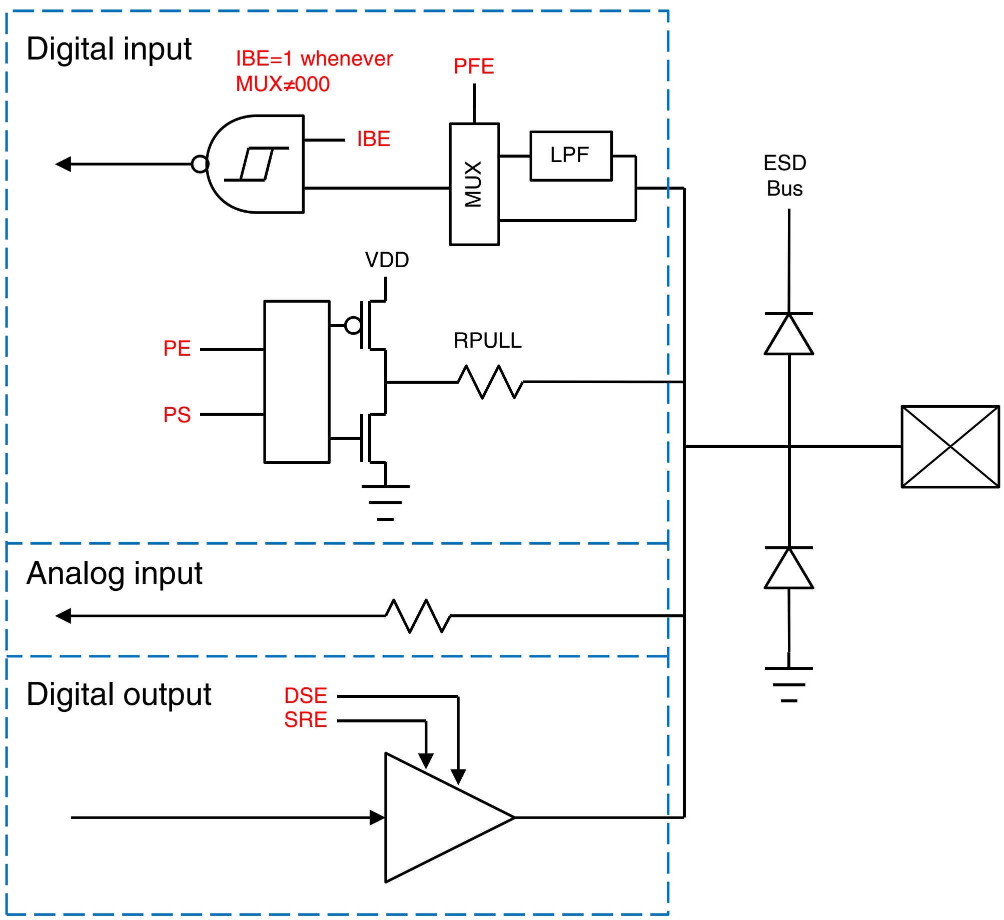


Figure 4. I/O simplified block diagram

The PORT module has the following features:

- all PIN support interrupt enable .

- Configurable edge(rising,falling,both) or level sensitive interrupt type
- Support DMA request
- Asynchronous wake-up in low-power modes
- Configurable pullup, pulldown, and pull-disable on select pins
- Configurable high and low drive strength on selected pins
- Configurable fast and slow slew rates on selected pins
- Configurable passive filter on selected pins
- Individual mux control field supporting analog or pin disabled, GPIO, and up to chip-specific digital functions
- Pad configuration fields are functional in all digital pin muxing modes.

The GPIO module has the following features:

- Port Data Input register visible in all digital pin-multiplexing modes
- Port Data Output register with corresponding set/clear/toggle registers
- Port Data Direction register
- GPIO support single-cycle access via fast GPIO.

3 Memory map

This device contains various memories and memory-mapped peripherals which are located in a 4 GB memory space. The following figure shows the system memory and peripheral locations

64 LQFP	36 XFBGA	32 QFN	48 QFN	64 MAPBGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
20	—	—	15	H4	PTE24	DISABLED		PTE24		TPM0_CH0		I2C0_SCL		
21	—	—	16	H5	PTE25	DISABLED		PTE25		TPM0_CH1		I2C0_SDA		
22	F3	10	17	D3	PTA0	SWD_CLK		PTA0		TPM0_CH5				SWD_CLK
23	F4	11	18	D4	PTA1	DISABLED		PTA1	LPUART0_RX	TPM2_CH0				
24	E4	12	19	E5	PTA2	DISABLED		PTA2	LPUART0_TX	TPM2_CH1				
25	E5	13	20	D5	PTA3	SWD_DIO		PTA3	I2C1_SCL	TPM0_CH0				SWD_DIO
26	F5	14	21	G5	PTA4	NMI_b		PTA4	I2C1_SDA	TPM0_CH1				NMI_b
27	—	—	—	F5	PTA5	DISABLED		PTA5	USB_CLKIN	TPM0_CH2				
28	—	—	—	H6	PTA12	DISABLED		PTA12		TPM1_CH0				
29	—	—	—	G6	PTA13	DISABLED		PTA13		TPM1_CH1				
30	C3	15	22	G7	VDD	VDD	VDD							
31	C4	16	23	H7	VSS	VSS	VSS							
32	F6	17	24	H8	PTA18	EXTAL0	EXTAL0	PTA18		LPUART1_RX	TPM_CLKIN0			
33	E6	18	25	G8	PTA19	XTAL0	XTAL0	PTA19		LPUART1_TX	TPM_CLKIN1		LPTMR0_ALT1	
34	D5	19	26	F8	PTA20	RESET_b		PTA20						RESET_b
35	D6	20	27	F7	PTB0/ LLWU_P5	ADC0_SE8	ADC0_SE8	PTB0/ LLWU_P5	I2C0_SCL	TPM1_CH0	SPI1_MOSI	SPI1_MISO		
36	C6	21	28	F6	PTB1	ADC0_SE9	ADC0_SE9	PTB1	I2C0_SDA	TPM1_CH1	SPI1_MISO	SPI1_MOSI		
37	—	—	29	E7	PTB2	ADC0_SE12	ADC0_SE12	PTB2	I2C0_SCL	TPM2_CH0				
38	—	—	30	E8	PTB3	ADC0_SE13	ADC0_SE13	PTB3	I2C0_SDA	TPM2_CH1				
39	—	—	31	E6	PTB16	DISABLED		PTB16	SPI1_MOSI	LPUART0_RX	TPM_CLKIN0	SPI1_MISO		
40	—	—	32	D7	PTB17	DISABLED		PTB17	SPI1_MISO	LPUART0_TX	TPM_CLKIN1	SPI1_MOSI		
41	—	—	—	D6	PTB18	DISABLED		PTB18		TPM2_CH0				
42	—	—	—	C7	PTB19	DISABLED		PTB19		TPM2_CH1				
43	—	—	33	D8	PTC0	ADC0_SE14	ADC0_SE14	PTC0		EXTRG_IN	audioUSB_SOF_OUT	CMP0_OUT		
44	C5	22	34	C6	PTC1/ LLWU_P6/ RTC_CLKIN	ADC0_SE15	ADC0_SE15	PTC1/ LLWU_P6/ RTC_CLKIN	I2C1_SCL		TPM0_CH0			
45	B6	23	35	B7	PTC2	ADC0_SE11	ADC0_SE11	PTC2	I2C1_SDA		TPM0_CH1			
46	B5	24	36	C8	PTC3/ LLWU_P7	DISABLED		PTC3/ LLWU_P7	SPI1_SCK	LPUART1_RX	TPM0_CH2	CLKOUT		
47	—	—	—	E3	VSS	VSS	VSS							
48	—	—	—	E4	VDD	VDD	VDD							
49	A6	25	37	B8	PTC4/ LLWU_P8	DISABLED		PTC4/ LLWU_P8	SPI0_PCS0	LPUART1_TX	TPM0_CH3	SPI1_PCS0		

Table 19. LPTMR0 signal descriptions

Chip signal name	Module signal name	Description	I/O
LPTMR0_ALT[3:1]	LPTMR0_ALT*n*	Pulse Counter Input pin	I

Table 20. RTC signal descriptions

Chip signal name	Module signal name	Description	I/O
RTC_CLKOUT[1]	RTC_CLKOUT	1 Hz square-wave output or OSCERCLK	O

1. RTC_CLKOUT can also be driven with OSCERCLK via SIM control bit SIM_SOPT[RCTCLKOUTSEL]

4.3.6 Communication interfaces

Table 21. USB FS OTG Signal Descriptions

Chip signal name	Module signal name	Description	I/O
USB0_DM	usb_dm	USB D- analog data signal on the USB bus.	I/O
USB0_DP	usb_dp	USB D+ analog data signal on the USB bus.	I/O
USB_CLKIN	—	Alternate USB clock input	I

Table 22. SPI0 signal descriptions

Chip signal name	Module signal name	Description	I/O
SPI0_MISO	MISO	Master Data In, Slave Data Out	I/O
SPI0_MOSI	MOSI	Master Data Out, Slave Data In	I/O
SPI0_SCLK	SPSCK	SPI Serial Clock	I/O
SPI0_PCS0	$\overline{SS}$	Slave Select	I/O

Table 23. SPI1 signal descriptions

Chip signal name	Module signal name	Description	I/O
SPI1_MISO	MISO	Master Data In, Slave Data Out	I/O
SPI1_MOSI	MOSI	Master Data Out, Slave Data In	I/O
SPI1_SCLK	SPSCK	SPI Serial Clock	I/O
SPI1_PCS0	$\overline{SS}$	Slave Select	I/O

Table 24. I²C0 signal descriptions

Chip signal name	Module signal name	Description	I/O
I2C0_SCL	SCL	Bidirectional serial clock line of the I²C system.	I/O
I2C0_SDA	SDA	Bidirectional serial data line of the I²C system.	I/O

Table 25. I²C1 signal descriptions

Chip signal name	Module signal name	Description	I/O
I2C1_SCL	SCL	Bidirectional serial clock line of the I²C system.	I/O
I2C1_SDA	SDA	Bidirectional serial data line of the I²C system.	I/O

Table 26. LPUART0 signal descriptions

Chip signal name	Module signal name	Description	I/O
LPUART0_TX	TxD	Transmit data	I/O
LPUART0_RX	RxD	Receive data	I

Table 27. LPUART1 signal descriptions

Chip signal name	Module signal name	Description	I/O
LPUART1_TX	TxD	Transmit data	I/O
LPUART1_RX	RxD	Receive data	I

Table 28. UART2 signal descriptions

Chip signal name	Module signal name	Description	I/O
UART2_TX	TxD	Transmit data	O
UART2_RX	RxD	Receive data	I

Table 29. FlexIO signal descriptions

Chip signal name	Module signal name	Description	I/O
FXIO0_Dx	FXIO_Dn (n=0...7)	Bidirectional FlexIO Shifter and Timer pin inputs/outputs	I/O

NOTE

The 48 QFN package for this product is not yet available. However, it is included in Package Your Way program for Kinetis MCUs. Visit freescale.com/KPYW for more details.

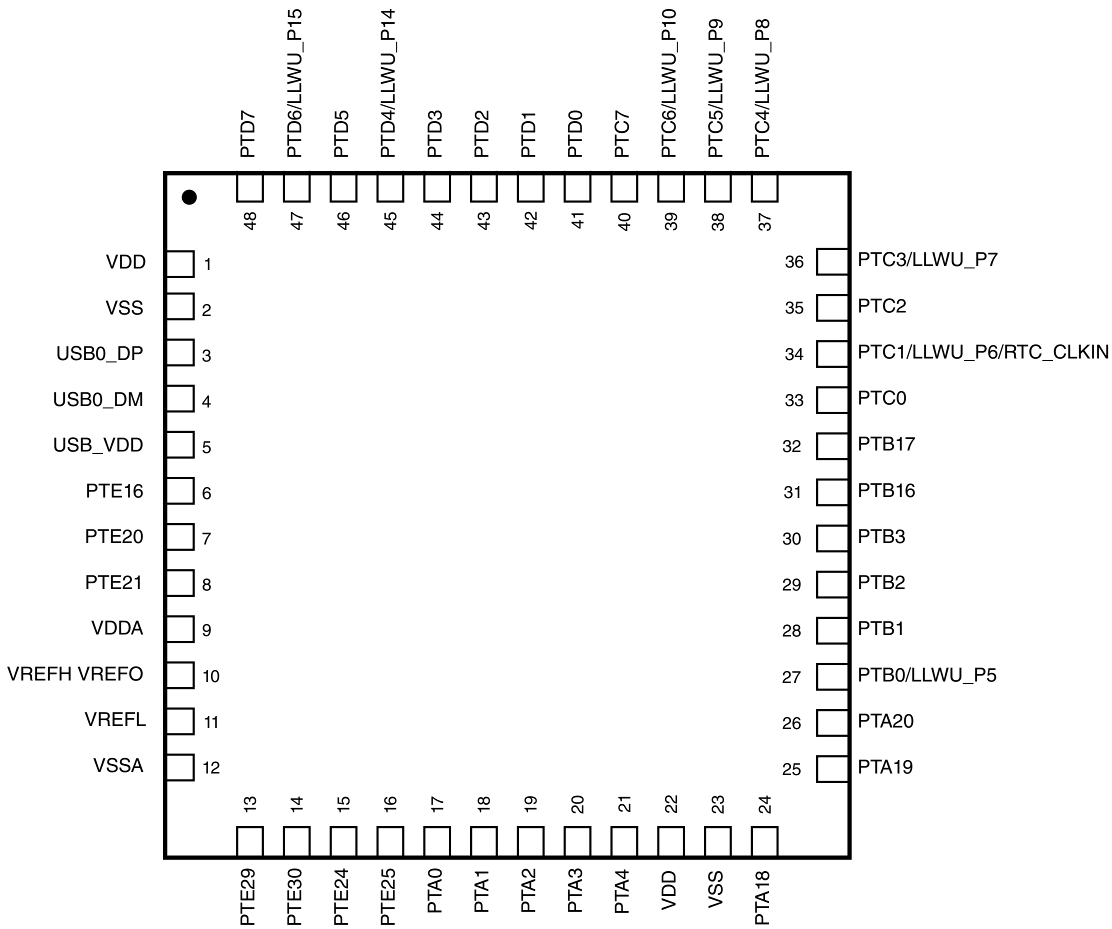
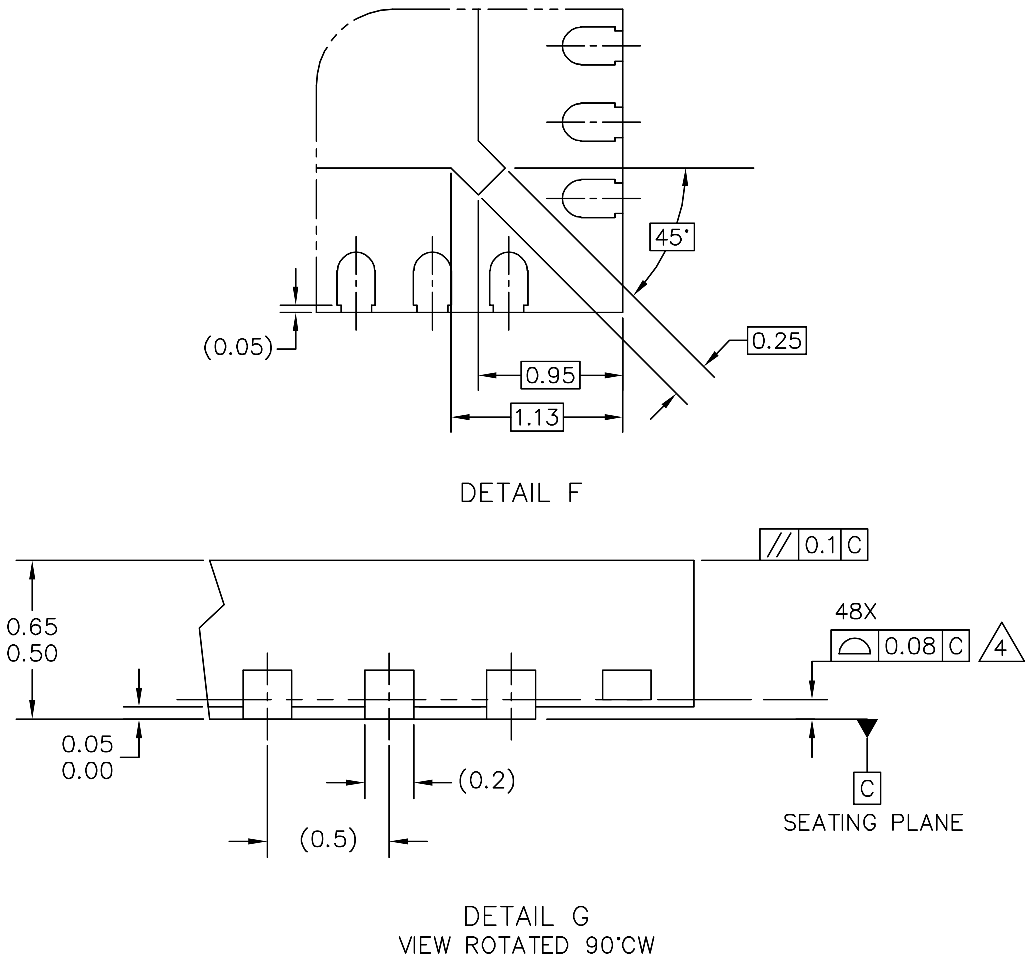


Figure 7. 48 QFN Pinout diagram (transparent top view)

The figure below shows the 64 MAPBGA pinouts.

NOTE

The 64 MAPBGA package for this product is not yet available. However, it is included in Package Your Way program for Kinetis MCUs. Visit freescale.com/KPYW for more details.



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M—1994.
3. THIS IS A NON—JEDEC REGISTERED PACKAGE.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

Figure 15. 48-pin QFN package dimension 2

5.2.2.1 Voltage and current operating requirements

Table 35. Voltage and current operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
V_{DD}	Supply voltage	1.71	3.6	V	1
USB_V_{DD}	Supply voltage	3.0	3.6	V	2
V_{DDA}	Analog supply voltage	1.71	3.6	V	
$V_{DD} – V_{DDA}$	V_{DD}-to-V_{DDA} differential voltage	–0.1	0.1	V	
$V_{SS} – V_{SSA}$	V_{SS}-to-V_{SSA} differential voltage	–0.1	0.1	V	
V_{IH}	Input high voltage • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V	 0.7 × V_{DD} 0.75 × V_{DD}	 — —	 V V	
V_{IL}	Input low voltage • 2.7 V ≤ V_{DD} ≤ 3.6 V • 1.7 V ≤ V_{DD} ≤ 2.7 V	 — —	 0.35 × V_{DD} 0.3 × V_{DD}	 V V	
V_{HYS}	Input hysteresis	0.06 × V_{DD}	—	V	
I_{ICIO}	IO pin negative DC injection current — single pin • V_{IN} < V_{SS}-0.3V	-3	—	mA	3
I_{ICcont}	Contiguous pin DC injection current —regional limit, includes sum of negative injection currents of 16 contiguous pins • Negative current injection	-25	—	mA	
V_{ODPU}	Open drain pullup voltage level	V_{DD}	V_{DD}	V	4
V_{RAM}	V_{DD} voltage required to retain RAM	1.2	—	V	

1. To use USB for 36XFBGA package, you need to limit the minimum value to 3.0V.
2. The power pin for USB and for other part of the chip is bonded together on the 36XFBGA package. The ripple limit for USB_VDD is 100 mV.
3. All I/O pins are internally clamped to V_{SS} through a ESD protection diode. There is no diode connection to V_{DD}. If V_{IN} greater than V_{IO_MIN} (= V_{SS}-0.3 V) is observed, then there is no need to provide current limiting resistors at the pads. If this limit cannot be observed then a current limiting resistor is required. The negative DC injection current limiting resistor is calculated as $R = (V_{IO\_MIN} - V_{IN})/|I_{ICIO}|$.
4. Open drain outputs must be pulled to V_{DD}.

5.2.2.2 LVD and POR operating requirements

Table 36. V_{DD} supply LVD and POR operating requirements

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{POR}	Falling V_{DD} POR detect voltage	0.8	1.1	1.5	V	—
V_{LVDH}	Falling low-voltage detect threshold — high range (LVDV = 01)	2.48	2.56	2.64	V	—
	Low-voltage warning thresholds — high range					1

Table continues on the next page...

Table 36. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{LVW1H} V_{LVW2H} V_{LVW3H} V_{LVW4H}	• Level 1 falling (LVWV = 00) • Level 2 falling (LVWV = 01) • Level 3 falling (LVWV = 10) • Level 4 falling (LVWV = 11)	2.62 2.72 2.82 2.92	2.70 2.80 2.90 3.00	2.78 2.88 2.98 3.08	V V V V	
V_{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	±60	—	mV	—
V_{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	—
V_{LVW1L} V_{LVW2L} V_{LVW3L} V_{LVW4L}	Low-voltage warning thresholds — low range • Level 1 falling (LVWV = 00) • Level 2 falling (LVWV = 01) • Level 3 falling (LVWV = 10) • Level 4 falling (LVWV = 11)	1.74 1.84 1.94 2.04	1.80 1.90 2.00 2.10	1.86 1.96 2.06 2.16	V V V V	1
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	±40	—	mV	—
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	—
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	μs	—

1. Rising thresholds are falling threshold + hysteresis voltage

5.2.2.3 Voltage and current operating behaviors

Table 37. Voltage and current operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
V_{OH}	Output high voltage — normal drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –5 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –2.5 mA	 V_{DD} – 0.5 V_{DD} – 0.5	 — —	 V V	1
V_{OH}	Output high voltage — high drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –20 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –10 mA	 V_{DD} – 0.5 V_{DD} – 0.5	 — —	 V V	1
I_{OHT}	Output high current total for all ports	—	100	mA	
V_{OL}	Output low voltage — normal drive pad • 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 5 mA • 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 2.5 mA	 — —	 0.5 0.5	 V V	1
V_{OL}	Output low voltage — high drive pad	 —	 0.5	 V	1

Table continues on the next page...

Table 39. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	• at 50°C • at 70°C • at 85°C • at 105 °C	— — —	2.21 3.59 8.02	2.80 4.18 9.47	μA	
I_{DD_VLLS0}	Very-low-leakage stop mode 0 current all peripheral disabled (SMC_STOPCTRL[PORPO] = 0) at 3.0 V • at 25 °C and below • at 50 °C • at 70 °C • at 85 °C • at 105 °C	— — — —	262 593 1430 2930 7930	360 725 2014 3514 9895	nA	
I_{DD_VLLS0}	Very-low-leakage stop mode 0 current all peripheral disabled (SMC_STOPCTRL[PORPO] = 1) at 3 V • at 25 °C and below • at 50 °C • at 70 °C • at 85 °C • at 105 °C	— — — —	87 417 1230 2720 7780	185 549 1230 3304 9745	nA	4

1. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
2. MCG_Lite configured for HIRC mode. CoreMark benchmark compiled using IAR 7.10 with optimization level high, optimized for balanced.
3. RTC uses external 32 kHz crystal as clock source, and the current includes ERCLK32K power consumption.
4. No brownout

Table 40. Low power mode peripheral adders — typical value

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
$I_{IRC8MHz}$	8 MHz internal reference clock (IRC) adder. Measured by entering STOP or VLPS mode with 8 MHz IRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	77	77	77	77	77	77	μA
$I_{IRC2MHz}$	2 MHz internal reference clock (IRC) adder. Measured by entering STOP mode with the 2 MHz IRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	25	25	25	25	25	25	μA

Table continues on the next page...

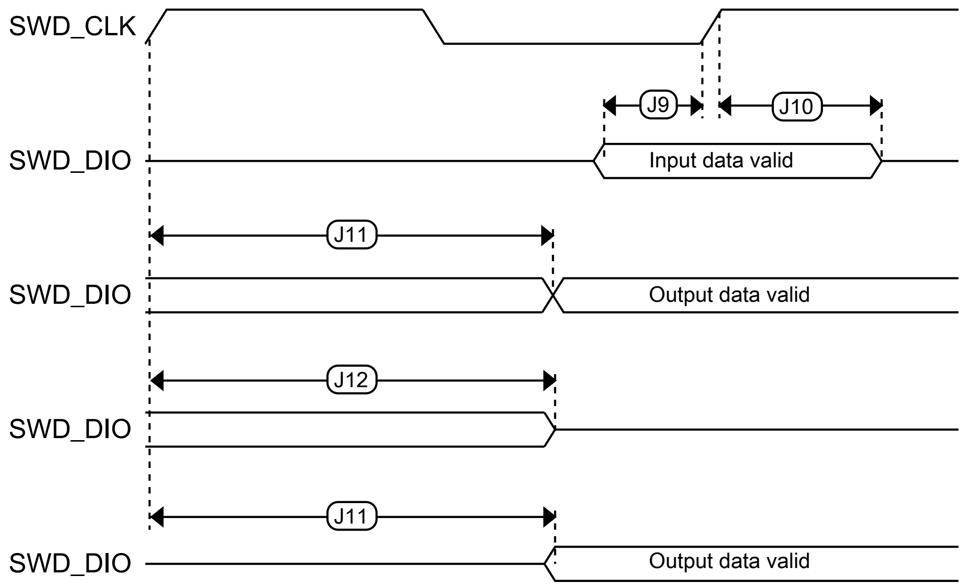


Figure 23. Serial wire data timing

5.3.2 System modules

There are no specifications necessary for the device's system modules.

5.3.3 Clock modules

5.3.3.1 MCG-Lite specifications

Table 47. IRC48M specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I_{DD48M}	Supply current	—	400	500	µA	
f_{irc48m}	Internal reference frequency	—	48	—	MHz	
$\Delta f_{irc48m\_ol\_lv}$	Open loop total deviation of IRC48M frequency at low voltage (VDD=1.71V-1.89V) over temperature	—	± 0.5	± 1.5	$\%f_{irc48m}$	
$\Delta f_{irc48m\_ol\_hv}$	Open loop total deviation of IRC48M frequency at high voltage (VDD=1.89V-3.6V) over temperature	—	± 0.5	± 1.0	$\%f_{irc48m}$	1
Δf_{irc48m_cl}	Closed loop total deviation of IRC48M frequency over voltage and temperature	—	—	± 0.1	$\%f_{host}$	2

Table continues on the next page...

Table 56. 16-bit ADC characteristics ($V_{REFH} = V_{DDA}$, $V_{REFL} = V_{SSA}$) (continued)

Symbol	Description	Conditions[1]	Min.	Typ.[2]	Max.	Unit	Notes
		• Avg = 32					
SFDR	Spurious free dynamic range	16-bit differential mode • Avg = 32	82	95	—	dB	7
		16-bit single-ended mode • Avg = 32	78	90	—	dB	
E_{IL}	Input leakage error		$I_{In} \times R_{AS}$			mV	I_{In} = leakage current (refer to the MCU's voltage and current operating ratings)
	Temp sensor slope	Across the full temperature range of the device	1.55	1.62	1.69	mV/°C	8
V_{TEMP25}	Temp sensor voltage	25 °C	706	716	726	mV	8

1. All accuracy numbers assume the ADC is calibrated with $V_{REFH} = V_{DDA}$
2. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
7. Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.
8. ADC conversion clock < 3 MHz

This device cannot support Host mode operation.

5.5.2 SPI switching specifications

The Serial Peripheral Interface (SPI) provides a synchronous serial bus with master and slave operations. Many of the transfer attributes are programmable. The following tables provide timing characteristics for classic SPI timing modes. See the SPI chapter of the chip's Reference Manual for information about the modified transfer formats used for communicating with slower peripheral devices.

All timing is shown with respect to 20% V_{DD} and 80% V_{DD} thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all SPI pins.

Table 61. SPI master mode timing on slew rate disabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	1024 x t_{periph}	ns	—
6	t_{SU}	Data setup time (inputs)	18	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	15	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. t_{periph} = 1/f_{periph}

Table 62. SPI master mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—

Table continues on the next page...

Table 64. SPI slave mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCK}	SPSCK period	4 x t_{periph}	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	—	ns	—
6	t_{SU}	Data setup time (inputs)	2	—	ns	—
7	t_{HI}	Data hold time (inputs)	7	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	122	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

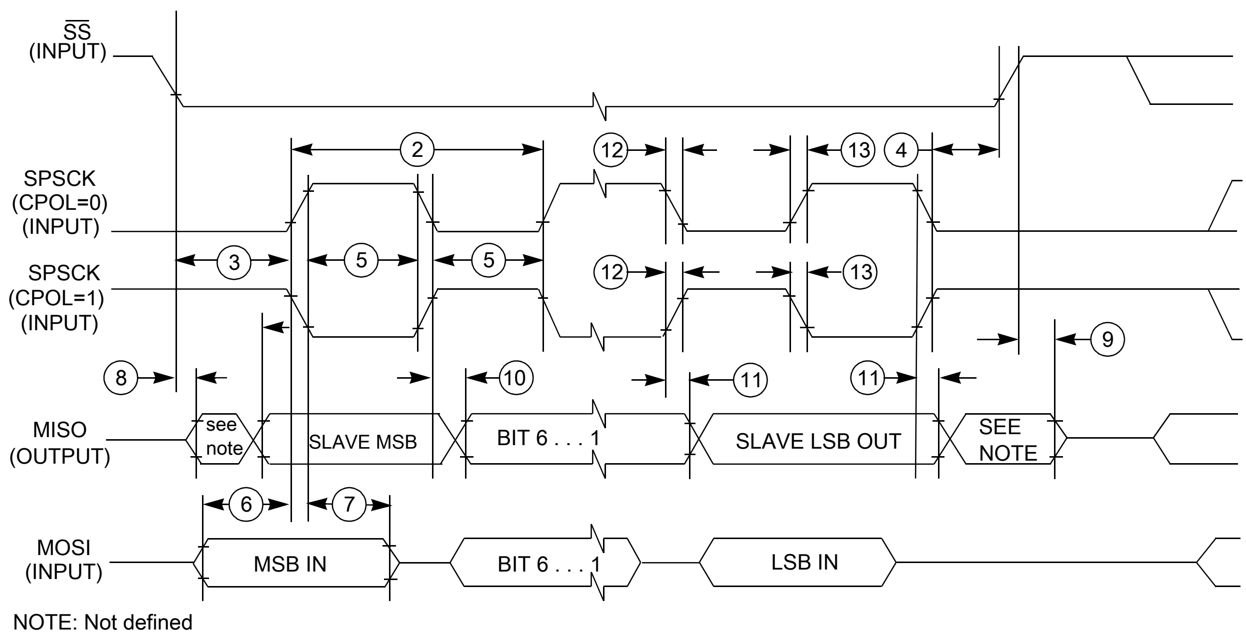


Figure 31. SPI slave mode timing (CPHA = 0)

2. The master mode I^2C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no slaves acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
3. The maximum tHD; DAT must be met only if the device does not stretch the LOW period (tLOW) of the SCL signal.
4. Input signal Slew = 10 ns and Output Load = 50 pF
5. Set-up time in slave-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.
6. A Fast mode I^2C bus device can be used in a Standard mode I2C bus system, but the requirement $t_{SU;\ DAT} \geq 250$ ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{rmax} + t_{SU;\ DAT} = 1000 + 250 = 1250$ ns (according to the Standard mode I^2C bus specification) before the SCL line is released.
7. C_b = total capacitance of the one bus line in pF.

To achieve 1MHz I2C clock rates, consider the following recommendations:

- To counter the effects of clock stretching, the I2C baud Rate select bits can be configured for faster than desired baud rate.
- Use high drive pad and DSE bit should be set in PORTx_PCRn register.
- Minimize loading on the I2C SDA and SCL pins to ensure fastest rise times for the SCL line to avoid clock stretching.
- Use smaller pull up resistors on SDA and SCL to reduce the RC time constant.

Table 66. I^2C 1Mbit/s timing

Characteristic	Symbol	Minimum	Maximum	Unit
SCL Clock Frequency	f_{SCL}	0	1[1]	MHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	0.26	—	µs
LOW period of the SCL clock	t_{LOW}	0.5	—	µs
HIGH period of the SCL clock	t_{HIGH}	0.26	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	0.26	—	µs
Data hold time for I_2C bus devices	t_{HD}; DAT	0	—	µs
Data set-up time	t_{SU}; DAT	50	—	ns
Rise time of SDA and SCL signals	t_r	$20 + 0.1C_b$	120	ns
Fall time of SDA and SCL signals	t_f	$20 + 0.1C_b$[2]	120	ns
Set-up time for STOP condition	t_{SU}; STO	0.26	—	µs
Bus free time between STOP and START condition	t_{BUF}	0.5	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	0	50	ns

1. The maximum SCL clock frequency of 1 Mbit/s can support maximum bus loading when using the high drive pins across the full voltage range.
2. C_b = total capacitance of the one bus line in pF.